

NOTES:

1. MATERIAL:
HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING CONTACT: SEE TABLE ON SHEET 1
SOLDER BALL: SEE TABLE ON SHEET 1
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

2. PLATING FOR -2XX SERIES DASH NOS:
Au OVER Ni WITH SPECIAL CONTACT
GEOMETRY TO MEET REQUIREMENTS
OF TELCORDIA GR-1217-CORE:
CENTRAL OFFICE ENVIRONMENT.

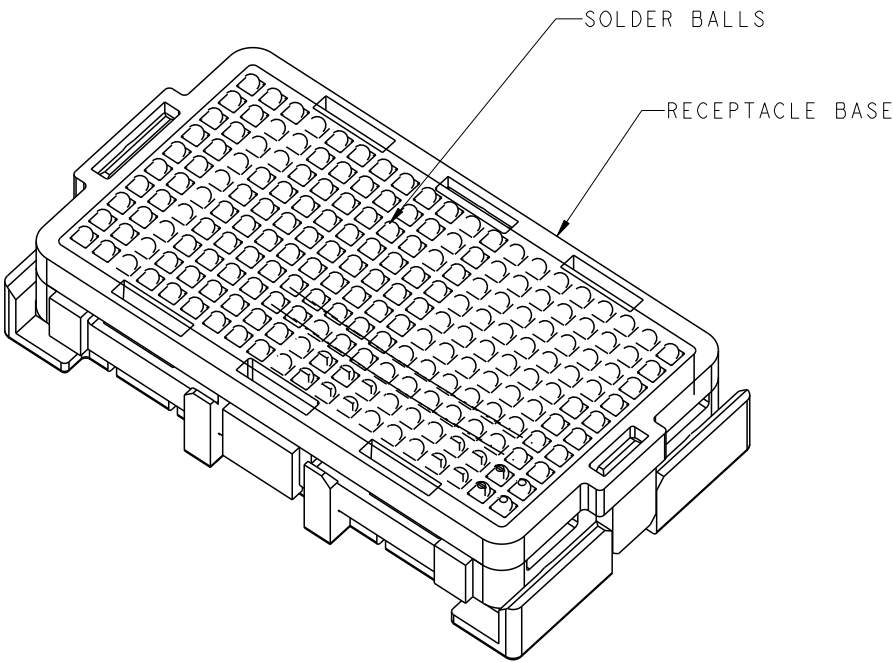
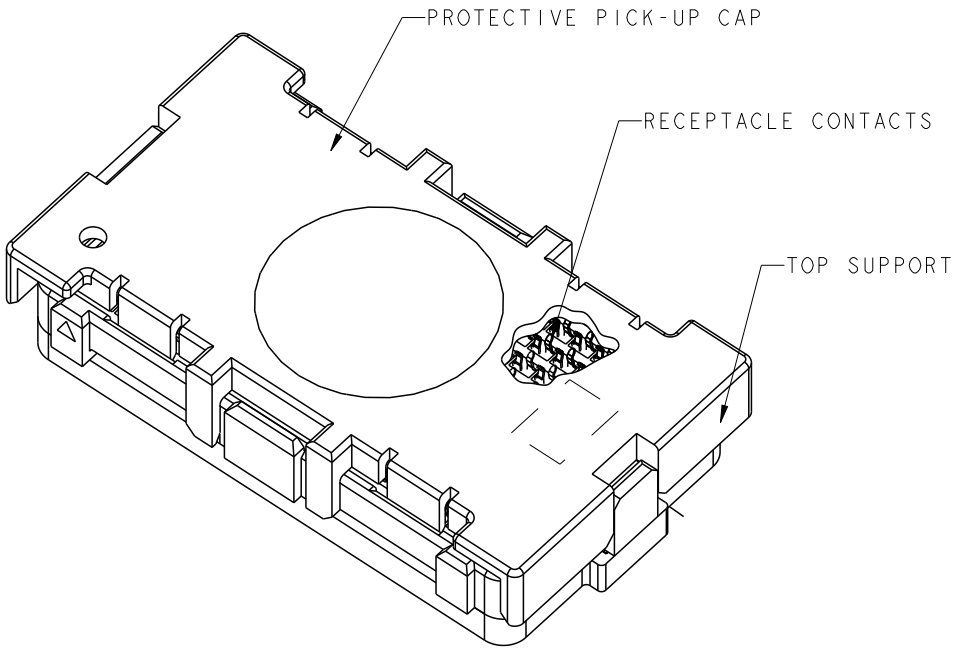
3. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE
DUE TO REFLOW ATTACHMENT.

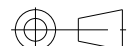
4. OVERALL BOARD-TO-BOARD STACK
HEIGHT WHEN MATED TO:
200 POSITION 0.0mm PLUG (84516) IS 6.0 REF.
200 POSITION 6.0mm PLUG (84530) IS 12.0 REF.

5. SEE SK-47284 FOR MATING RESTRICTIONS
WITH EARLIER DESIGN VERSIONS.

6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION
GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY
IN A LEADED SOLDER PROSESS DUE TO A HIGHER REFLOW TEMPERATURE
LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH
LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI
FCI APPLICATION SPECIFICATION

7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVE AND OTHER
COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004. PRODUCT
MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE
NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH
CHARACTER POSITION



spec ref				dr		wcadmin	2001/08/01		projection		mm		size		A3	scale		1:1																			
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED				eng		Dave Horchler		2013/01/22						ecn no				ELX-V-13917-1																	
						chr		-		-																											
						appr		R Marshall		2013/01/22						product family						MEG-ARRAY						rel level				Released					
surface		linear		0.X		±.3				title						6.0mm RECPT. ASSY						dwg no						55724						rev		J	
				0.XX		±.10																															
				0.XXX		±.050																															
		angular		0°		±°		www.fci.com		cat. no.						Product - Customer Drw						sheet 3 of 3															